7.6mmX7.6mm SUPER FLUX LED LAMP

Part Number: WP7676CSURC Hyper Red

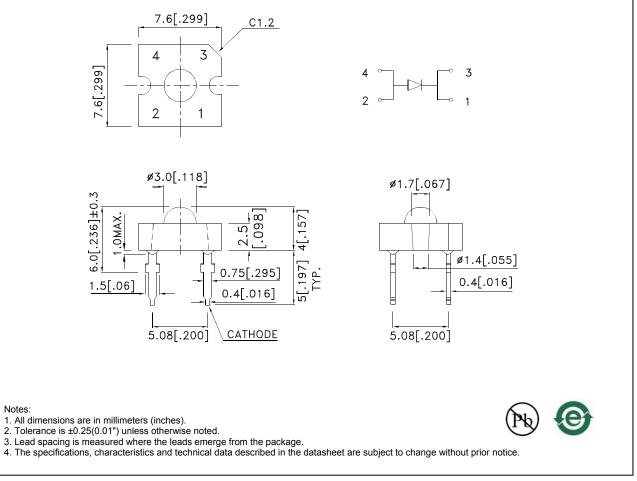
Features

- Super flux output.
- Design for high current operation.
- Outstanding material efficiency.
- Reliable and rugged.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

Package Dimensions



SPEC NO: DSAF2276 APPROVED: WYNEC REV NO: V.3A CHECKED: Allen Liu DATE: MAY/27/2014 DRAWN: L.Q.Xie PAGE: 1 OF 6 ERP: 1101007267

Selection Guide									
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Φv (lm) [2] @ 20mA	Viewing Angle [1]			
			Min.	Тур.	Тур.	201/2			
WP7676CSURC	Hyper Red (AlGaInP)	Water Clear	270	430	0.29	70°			
			*90	*170					

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.
Drive current between 10mA and 30mA are recommended for long term performance.

Operation at current below 10mA is not recommended.
* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	645		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	27		nm	IF=20mA
С	Capacitance	Hyper Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.9	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

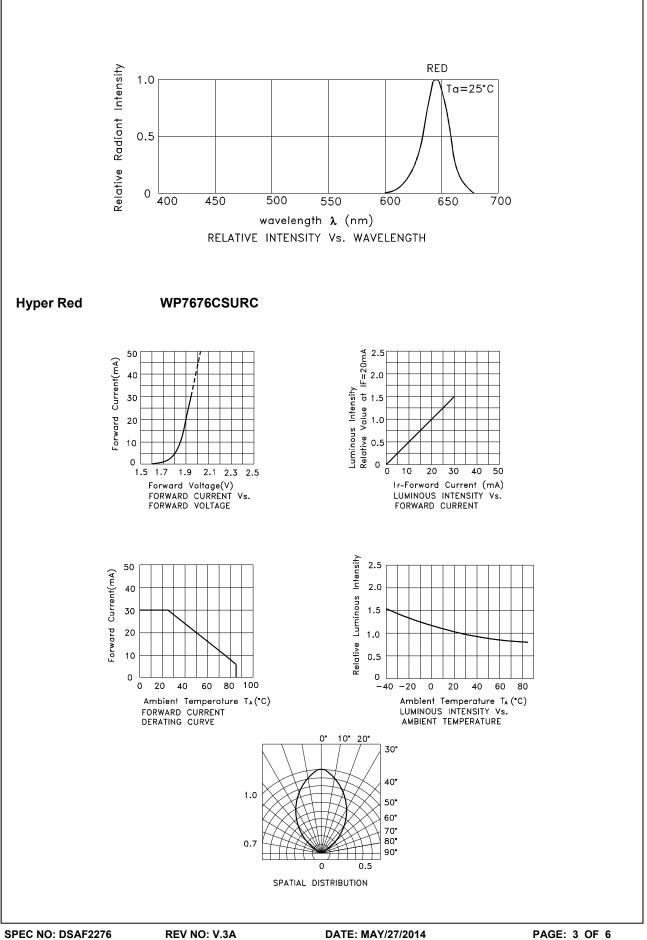
Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

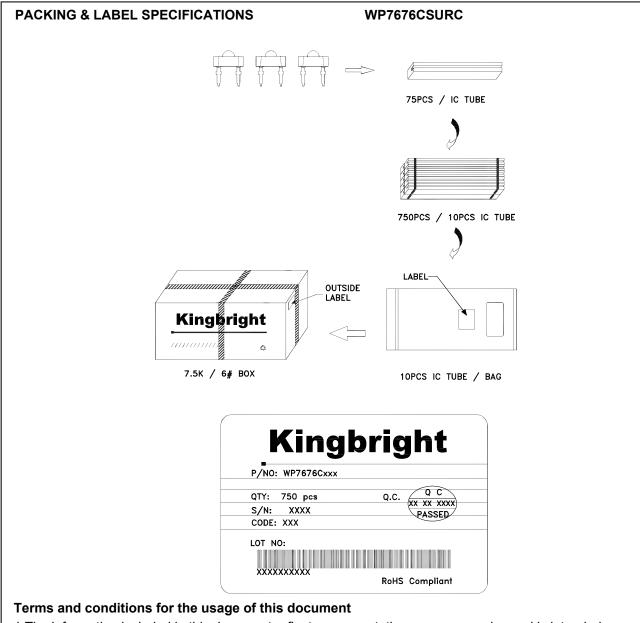
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.

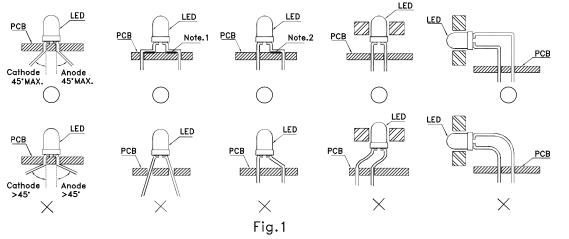




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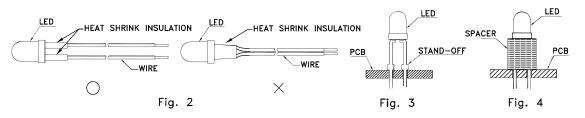
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

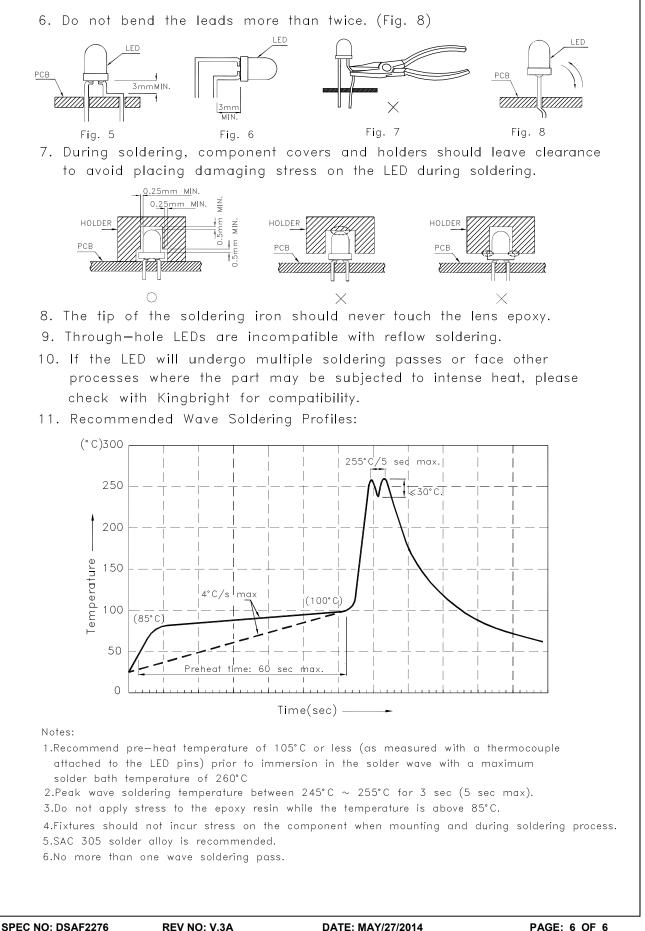


")" Correct mounting method "imes" Incorrect mounting method

- When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



DATE: MAY/27/2014 DRAWN: L.Q.Xie

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